

What Is Claimed Is:Sub
B1

1. An adhesive composition, comprising:
an insulating resin;
a photopolymerization initiator; and
an oxetan compound.

5

2. The adhesive composition according to Claim 1,
comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive
composition.

10

3. The anisotropic conductive adhesive composition
according to ~~Claim 1 or Claim 2~~, further comprising
electrically conductive particles.

15

4. A connected structure, wherein electrodes on a
plastic substrate and on a circuit board that are facing each
other are connected by the adhesive composition according to
~~any of Claims 1 to 3.~~

Add A1

Add B4

Add C2